# **Power MOSFET**

# 30 V, 88 A, Single N-Channel, DPAK/IPAK

#### **Features**

- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- NVD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

# **Applications**

- CPU Power Delivery
- DC-DC Converters
- Low Side Switching

# MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage	Drain-to-Source Voltage			30	V
Gate-to-Source Voltag	Gate-to-Source Voltage			±20	V
Continuous Drain		T <sub>A</sub> = 25°C	I <sub>D</sub>	17.4	Α
Current (R <sub>θJA</sub> ) (Note 1)		T <sub>A</sub> = 85°C		13.5	
Power Dissipation (R <sub>θJA</sub> ) (Note 1)		T <sub>A</sub> = 25°C	P <sub>D</sub>	2.65	W
Continuous Drain		T <sub>A</sub> = 25°C	I <sub>D</sub>	12.7	Α
Current (R <sub>θJA</sub> ) (Note 2)	Steady	T <sub>A</sub> = 85°C		9.8	
Power Dissipation (R <sub>θJA</sub> ) (Note 2)	State	T <sub>A</sub> = 25°C	P <sub>D</sub>	1.41	W
Continuous Drain		T <sub>C</sub> = 25°C	I <sub>D</sub>	95	Α
Current (R <sub>θJC</sub> ) (Note 1)		T <sub>C</sub> = 85°C		73	
Power Dissipation (R <sub>θJC</sub> ) (Note 1)		T <sub>C</sub> = 25°C	P <sub>D</sub>	79	W
Pulsed Drain Current	t <sub>p</sub> =10μs	T <sub>A</sub> = 25°C	I <sub>DM</sub>	175	Α
Current Limited by Pack	age	T <sub>A</sub> = 25°C	I <sub>DmaxPkg</sub>	45	Α
Operating Junction and	Operating Junction and Storage Temperature			-55 to 175	°C
Source Current (Body D	Source Current (Body Diode)			55	Α
Source Current (Body Diode) Pulsed t <sub>p</sub> =20 μs			I <sub>SM</sub>	175	Α
Drain to Source dV/dt			dV/dt	6.0	V/ns
Single Pulse Drain-to-Source Avalanche Energy ( $V_{DD}$ = 24 V, $V_{GS}$ = 10 V, L = 1.0 mH, $I_{L(pk)}$ = 24 A, $R_G$ = 25 $\Omega$ )			E <sub>AS</sub>	288	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

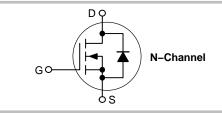
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



# ON Semiconductor®

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V <sub>(BR)DSS</sub> R <sub>DS(on)</sub> MAX		I <sub>D</sub> MAX	
30 V	5.0 mΩ @ 10 V	88 A	
	7.4 mΩ @ 4.5 V	00 A	



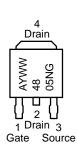


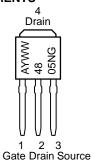
DPAK CASE 369AA (Bent Lead) STYLE 2



IPAK
CASE 369D
(Straight Lead DPAK)

# MARKING DIAGRAMS & PIN ASSIGNMENTS





A = Assembly Location\*

Y = Year
WW = Work Week
4805N = Device Code
G = Pb-Free Package

\* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

## ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

## THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{ heta JC}$	1.9	°C/W
Junction-to-TAB (Drain)	$R_{ heta JC-TAB}$	3.5	
Junction-to-Ambient - Steady State (Note 1)	$R_{ heta JA}$	56.6	
Junction-to-Ambient - Steady State (Note 2)	$R_{ heta JA}$	106.6	

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•		•		•	•	
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				27		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 \text{ V},$ $T_{J} = 25^{\circ}\text{C}$ $V_{DS} = 24 \text{ V}$ $T_{J} = 125^{\circ}\text{C}$				1.0 10	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V				±100	nA
ON CHARACTERISTICS (Note 3)					1	I	<u>.</u>
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$	l <sub>D</sub> = 250 μA	1.5		2.5	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				5.86		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 to	I <sub>D</sub> = 30 A		4.3	5.0	mΩ
	= = (=)	11.5 V	I <sub>D</sub> = 15 A		4.2		1
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 30 A		6.0	7.4	1
			I <sub>D</sub> = 15 A		5.8		1
Forward Transconductance	9FS	V <sub>DS</sub> = 15 V	, I <sub>D</sub> = 15 A		17		S
CHARGES AND CAPACITANCES	•		•		•		<u> </u>
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 12 \text{ V}$			2865		pF
Output Capacitance	C <sub>oss</sub>				610		
Reverse Transfer Capacitance	C <sub>rss</sub>	*DS =	'- v		338		1
Total Gate Charge	Q <sub>G(TOT)</sub>				20.5	26	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 4.5 V,	V <sub>DS</sub> = 15 V,		4.05		1
Gate-to-Source Charge	Q <sub>GS</sub>	I <sub>D</sub> = 3			8.28		1
Gate-to-Drain Charge	$Q_GD$				8.36		1
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 11.5 V <sub>D</sub>			48		nC
SWITCHING CHARACTERISTICS (Note 4)							
Turn-On Delay Time	t <sub>d(on)</sub>				17.2		ns
Rise Time	t <sub>r</sub>	$V_{GS} = 4.5 \text{ V}, V_{DS} = 15 \text{ V},$ $I_{D} = 15 \text{ A}, R_{G} = 3.0 \Omega$			20.3		
Turn-Off Delay Time	t <sub>d(off)</sub>				20.8		
Fall Time	t <sub>f</sub>				8.0		1
Turn-On Delay Time	t <sub>d(on)</sub>				10.8		ns
Rise Time	t <sub>r</sub>	$V_{GS}$ = 11.5 V, $V_{DS}$ = 15 V, $I_{D}$ = 15 A, $R_{G}$ = 3.0 $\Omega$			20.5		1
Turn-Off Delay Time	t <sub>d(off)</sub>				30.8		1
Fall Time	t <sub>f</sub>				4.4		

Surface–mounted on FR4 board using 1 in sq pad size, 1 oz Cu.
 Surface–mounted on FR4 board using the minimum recommended pad size.

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted) (continued)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	$V_{SD}$	$V_{SD}$ $V_{GS} = 0 V$ ,	T <sub>J</sub> = 25°C		0.87	1.2	V
		I <sub>S</sub> = 30 A	T <sub>J</sub> = 125°C		0.76		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, dls/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 30 \text{ A}$			25.7		ns
Charge Time	ta				13.1		
Discharge Time	tb				12.6		
Reverse Recovery Time	$Q_{RR}$				18		nC
PACKAGE PARASITIC VALUES							
Source Inductance	L <sub>S</sub>				2.49		nΗ
Drain Inductance, DPAK	L <sub>D</sub>	1			0.0164		
Drain Inductance, IPAK	L <sub>D</sub>	T <sub>A</sub> = 25°C			1.88		
Gate Inductance	L <sub>G</sub>				3.46		
Gate Resistance	$R_{G}$	1			0.8		Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width  $\leq 300~\mu$ s, Duty Cycle  $\leq 2\%$ .

4. Switching characteristics are independent of operating junction temperatures.

## **TYPICAL PERFORMANCE CURVES**

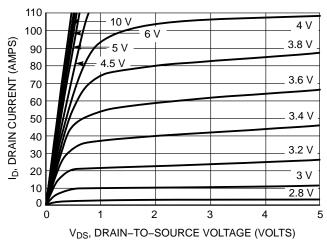


Figure 1. On-Region Characteristics

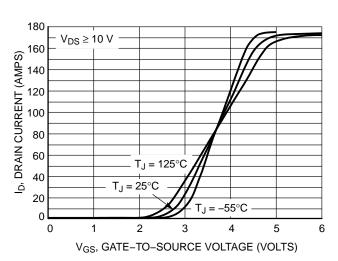


Figure 2. Transfer Characteristics

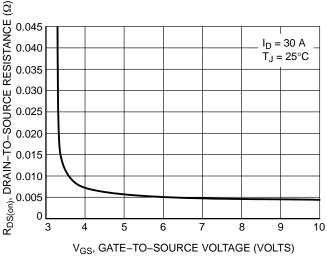


Figure 3. On–Resistance vs. Gate–to–Source Voltage

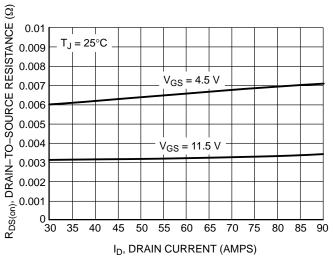


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

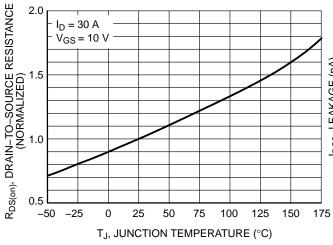


Figure 5. On–Resistance Variation with Temperature

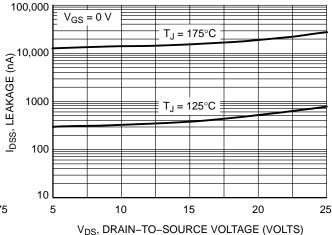
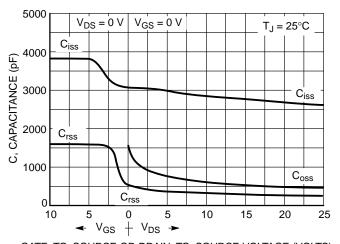


Figure 6. Drain-to-Source Leakage Current vs. Drain Voltage

#### **TYPICAL PERFORMANCE CURVES**



GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (VOLTS)

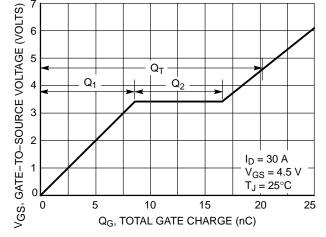


Figure 8. Gate-To-Source and Drain-To-Source
Voltage vs. Total Charge



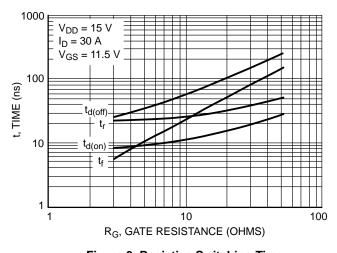


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

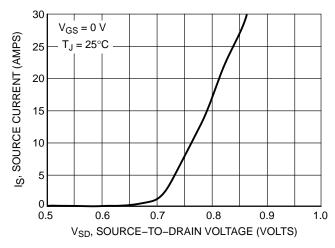


Figure 10. Diode Forward Voltage vs. Current

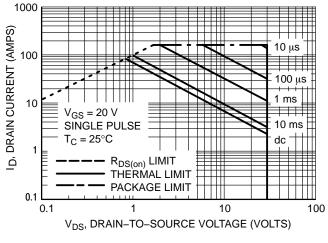


Figure 11. Maximum Rated Forward Biased Safe Operating Area

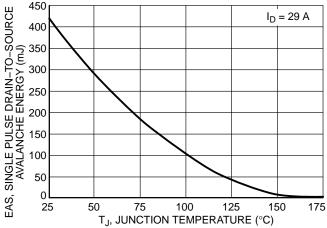


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

## **TYPICAL PERFORMANCE CURVES**

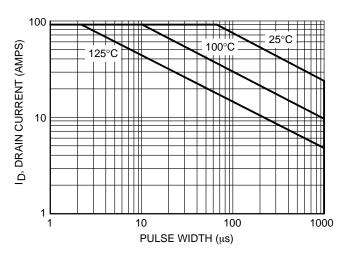


Figure 13. Avalanche Characteristics

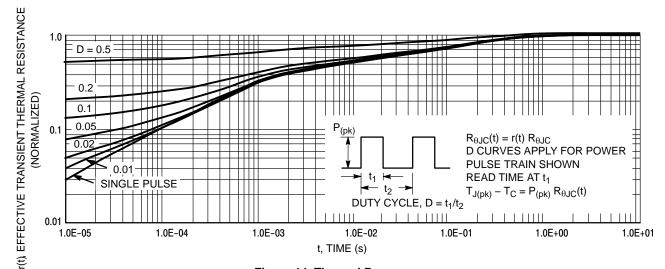


Figure 14. Thermal Response

# **ORDERING INFORMATION**

Order Number	Package	Shipping <sup>†</sup>
NTD4805NT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NTD4805N-1G	IPAK (Pb-Free)	75 Units / Rail
NVD4805NT4G*	DPAK (Pb-Free)	2,500 / Tape & Reel

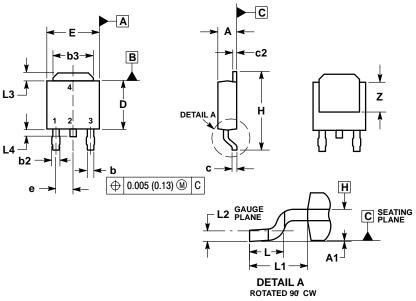
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NVD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

#### PACKAGE DIMENSIONS

# **DPAK (SINGLE GUAGE)**

CASE 369AA **ISSUE B** 



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: INCHES.

  3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.

  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.

  5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.

  6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INCHES		MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29	BSC	
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108	0.108 REF 2.74		REF	
L2	0.020	BSC	SSC 0.51 B		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

# **SOLDERING FOOTPRINT\***

#### 6.20 3.00 0.244 0.118 2.58 0.102 5.80 1.60 6.17 0.228 0.063 0.243

 $\left(\frac{mm}{inches}\right)$ SCALE 3:1

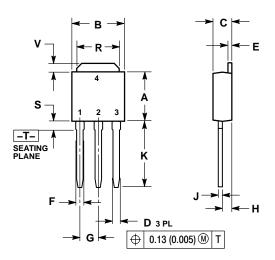
STYLE 2:

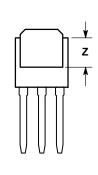
PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

## **IPAK** CASE 369D **ISSUE C**





#### NOTES

- DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETER		
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.245	5.97	6.35	
В	0.250	0.265	6.35	6.73	
С	0.086	0.094	2.19	2.38	
D	0.027	0.035	0.69	0.88	
Е	0.018	0.023	0.46	0.58	
F	0.037	0.045	0.94	1.14	
G	0.090	0.090 BSC 2.2		BSC	
Н	0.034	0.040	0.87	1.01	
J	0.018	0.023	0.46	0.58	
Κ	0.350	0.380	8.89	9.65	
R	0.180	0.215	4.45	5.45	
S	0.025	0.040	0.63	1.01	
٧	0.035	0.050	0.89	1.27	
Z	0.155		3.93		

STYLE 2:

PIN 1. GATE

- 2.
- DRAIN SOURCE 3.
- DRAIN

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